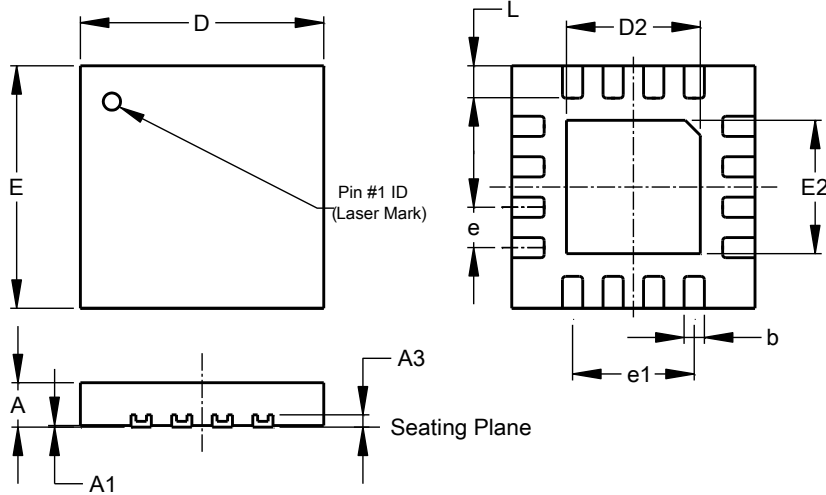


Package Outline Dimensions

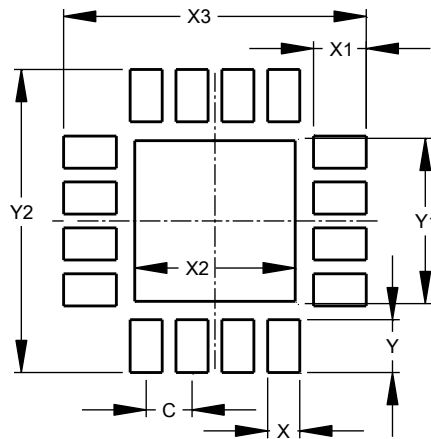
U-QFN3030-16 (Type US)



U-QFN3030-16 (Type US)			
Dim	Min	Max	Typ
A	0.500	0.600	0.550
A1	0.000	0.050	--
A3	0.152 REF		
b	0.200	0.300	0.250
D	2.950	3.050	3.000
D2	1.600	1.700	1.650
e	0.500 BSC		
e1	1.500 REF		
E	2.950	3.050	3.000
E2	1.600	1.700	1.650
L	0.350	0.450	0.400
All Dimensions in mm			

Suggested Pad Layout

U-QFN3030-16 (Type US)



Dimensions	Value (in mm)
C	0.500
X	0.350
X1	0.570
X2	1.800
X3	3.300
Y	0.570
Y1	1.800
Y2	3.300

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.